ABSTRACT

METHOD FOR MANUFACTURING INTEGRATED DEVICE PACKAGES

Preparation for fabricating an integrated device package is conducted by forming a first non-conductive dielectric layer on a first side of a plurality of dies and a first non-conductive dielectric layer on a first side of a carrier. The plurality of dies is bonded sequentially to the carrier by adhering the respective non-conductive dielectric layers to each other. A filling non-conductive dielectric layer is formed on the carrier and the plurality of dies until the plurality of dies is covered by the filling non-conductive dielectric layer. A portion of the filling non-conductive dielectric layer is then removed to planarize and expose conductive contact pads located on a second side of the plurality of dies opposite to the first side, to form a reconstituted die assembly which is electrically connectable to an external electronic device.

(FIG. 5)